# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

HP OMEN Pro 15 Notebook, HP OMEN Pro, HP OMEN Pro 15

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCB</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD; LED</td>
<td>2</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>PCB</td>
<td>892</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Wire; FFC</td>
<td>9</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Phillips Screwdriver</td>
<td>1# 2.55-3.00 kgf-cm</td>
</tr>
<tr>
<td>Description #2 Phillips Screwdriver</td>
<td>0# 1.35-1.84 kgf-cm</td>
</tr>
<tr>
<td>Description #3 Screwdriver for outer hex screw</td>
<td>4mm, 2.55-3.00 kgf-cm</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1.  Remove 4pcs rubber foot. (Figure 1)
2.  Remove 12pcs M2L4.5 screw (Figure 2)
3.  Remove L-case (Figure 3)
4.  Remove 2pcs M2L3.5 screw to release battery (Figure 4)
5.  Remove 4pcs M2L3.5 screw to release thermal module (Figure 5)
6.  Remove 2pcs M2L2.5 screw to release SSD card and WLAN card (Figure 6)
7.  Remove 1pcs hex screw(4mm) on MB (Figure 7)
8.  Remove 3pcs M2L2.5 screw to release mother board (Figure 8)
9.  Remove 2pcs M2L3.5 screw to release speaker (Figure 9)
10. Remove 5 pcs M1.6L2 screw to release TP module (Figure 10)
11. Remove 2pcs M2L2.5 screw to release DC-in bracket (Figure 11)
12. Remove 1pcs M2L2.5 screw to release Power board (Figure 12)
13. Remove 4pcs M2L2.5 screw to release airvent lighting module (Figure 13)
14. Remove 6pcs M2.5L3 screw to release Hinge from U-case (Figure 14)
15. Separate system and hinge-up (Figure 15)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Disassemble process - 1

1-1 Remove 4 pcs rubber foot
1-2 Remove 12 pcs M2L4.5 screw
1-3 Remove L-case
Disassemble process - 2

2-1 Remove 2pcs M2L3.5 screw to release battery
2-2 Remove 4pcs M2L3.5 screw to release thermal module
2-3 Remove 2pcs M2L2.5 screw to release SSD card and WLAN card
Disassemble process - 3

3-1 Remove 1 pcs hex screw(4mm) on MB
3-2 Remove 3pcs M2L2.5 screw to release mother board
3-3 Remove 2 pcs M2L3.5 screw to release speaker
Disassemble process - 4

4-1 Remove 5 pcs M1.6L2 screw to release TP module
4-2 Remove 2pcs M2L2.5 screw to release DC-in bracket
4-3 Remove 1pcs M2L2.5 screw to release Power board
Disassemble process - 5

5-1 Remove 4 pcs M2L2.5 screw to release airvent lighting module

5-2 Remove 6pcs M2.5L3 screw to release Hinge from U-case

5-3 Separate system and hinge-up